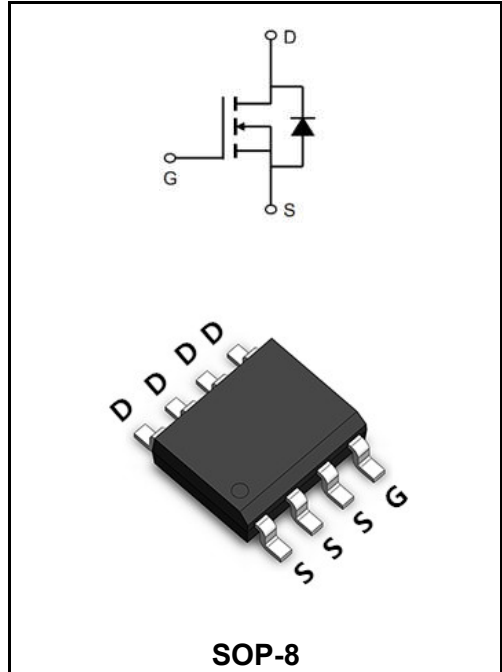


**20V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	15A
<b>V<sub>DSS</sub></b>	20V
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=4.5V)</sub></b>	< 8.0mΩ ( <b>Type:6.3 mΩ</b> )



**Application**

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW15N02S	SOP-8	YFW 15N02S XXXXX	3000PCS/Tape

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	<b>V<sub>DS</sub></b>	20	<b>V</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±20	<b>V</b>
Continuous Drain Current T <sub>c</sub> =25°C	<b>I<sub>D</sub></b>	15	<b>A</b>
Continuous Drain Current T <sub>c</sub> =100°C	<b>I<sub>D</sub></b>	12	<b>A</b>
Pulsed Drain Current <sup>note1</sup>	<b>I<sub>DM</sub></b>	45	<b>A</b>
Single Pulse Avalanche Energy <sup>note2</sup>	<b>E<sub>AS</sub></b>	36	<b>mJ</b>
Total Power Dissipation T <sub>c</sub> =25°C	<b>P<sub>D</sub></b>	31	<b>W</b>
Thermal Resistance, Junction to Case	<b>R<sub>θJC</sub></b>	4.84	<b>°C/W</b>
Operating and Storage Temperature Range	<b>T<sub>J</sub> , T<sub>STG</sub></b>	-55 to +150	<b>°C</b>

**Maximum Ratings at Tc=25°C unless otherwise specified**

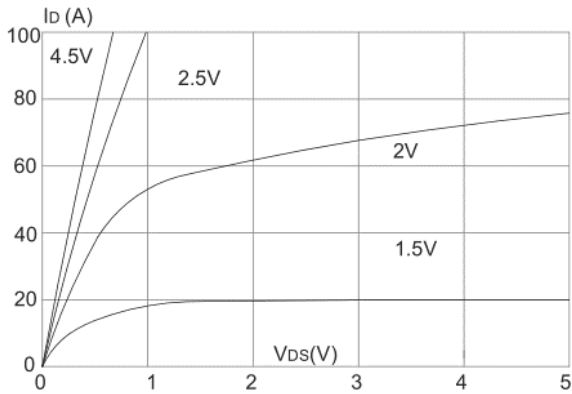
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	20	22	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$	<b>I<sub>DSS</sub></b>	-	-	1.0	<b>μA</b>
Gate to Body Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	0.4	0.7	1.1	<b>V</b>
Static Drain-Source On-Resistance note3	$V_{GS}=4.5V, I_D=25A$	<b>R<sub>DS(ON)</sub></b>	-	6.3	8.0	<b>mΩ</b>
	$V_{GS}=2.5V, I_D=10A$		-	8.8	13	
Input Capacitance	$V_{DS}=10V$ $V_{GS}=0V$ $f=1.0MHz$	<b>C<sub>iss</sub></b>	-	1458	-	<b>μF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	238	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	212	-	
Total Gate Charge	$V_{DS}=10V$ $I_D=25A$ $V_{GS}=4.5V$	<b>Q<sub>g</sub></b>	-	19	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	3	-	
Gate-Drain("Miller") Charge		<b>Q<sub>gd</sub></b>	-	6.4	-	
Turn-on delay time	$V_{DS}=10V$ $I_D=10A$ $R_{GEN}=3\Omega$ $V_{GS}=4.5V$	<b>t<sub>d(on)</sub></b>	-	10	-	<b>ns</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	21	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	39	-	
Turn- Off Fall Time		<b>t<sub>f</sub></b>	-	19	-	
Maximum Continuous Drain to Source Diode Forward Current		<b>I<sub>S</sub></b>	-	-	50	<b>A</b>
Maximum Pulsed Drain to Source Diode Forward Current		<b>I<sub>SM</sub></b>	-	-	200	<b>A</b>
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=30A$	<b>V<sub>SD</sub></b>	-	-	1.2	<b>V</b>
Body Diode Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$	<b>t<sub>rr</sub></b>	-	25	-	<b>ns</b>
Body Diode Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	20	-	<b>nC</b>

**Notes:**

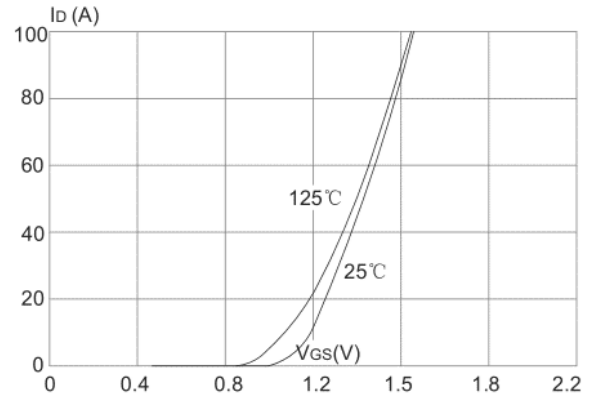
- 1、Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- 2、EAS condition:  $T_J=25^\circ C, V_{DD}=10V, V_G=4.5V, L=0.5mH, R_G=25\Omega, I_{AS}=12A$
- 3、Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

**Ratings and Characteristic Curves**

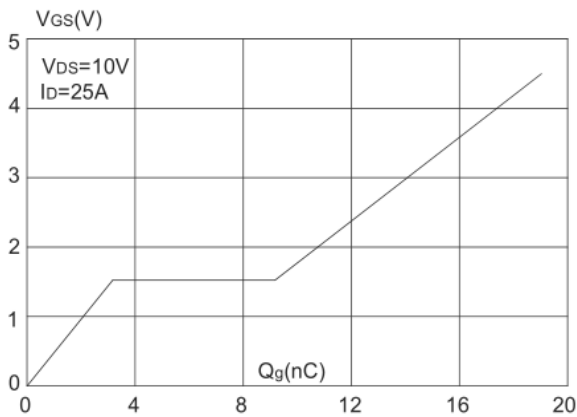
**Typical Characteristics**



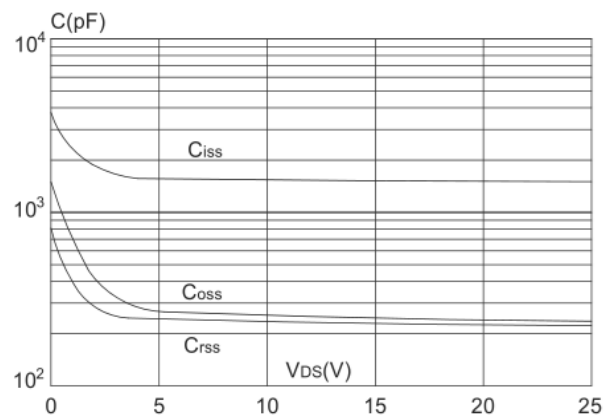
**Figure 1:** Output Characteristics



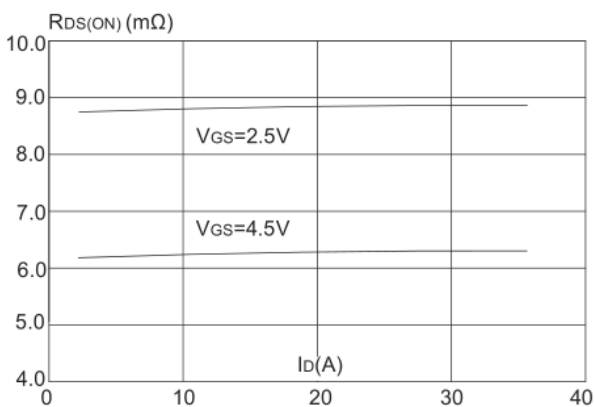
**Figure 2:** Typical Transfer Characteristics



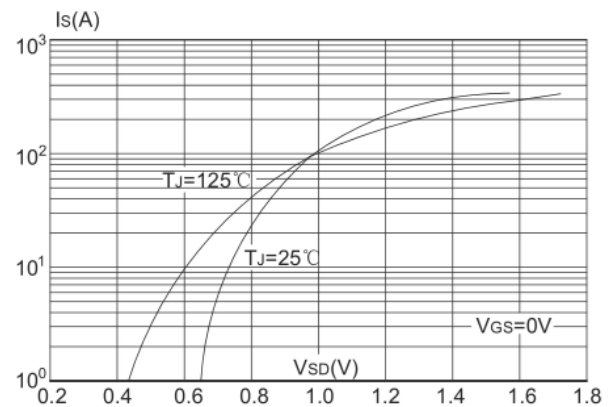
**Figure 3:** On-resistance vs. Drain Current



**Figure 4:** Body Diode Characteristics

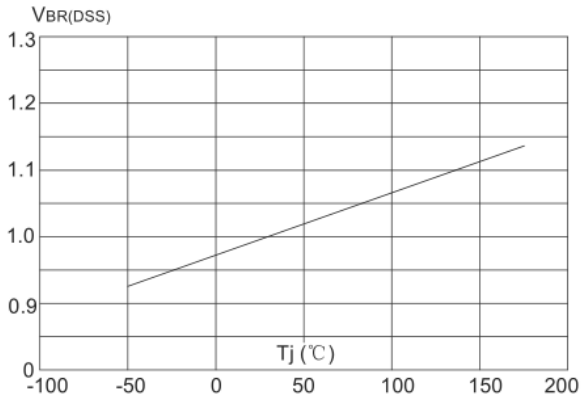


**Figure 5:** Gate Charge Characteristics

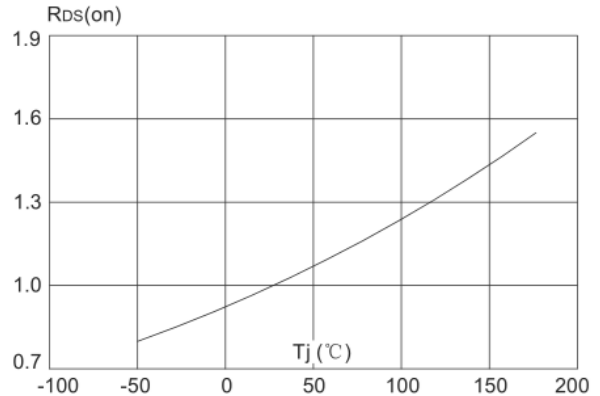


**Figure 6:** Capacitance Characteristics

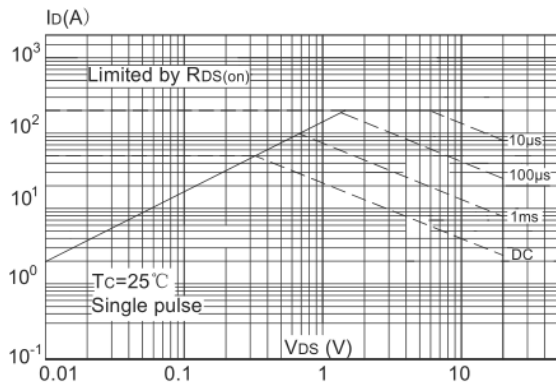
**Ratings and Characteristic Curves**



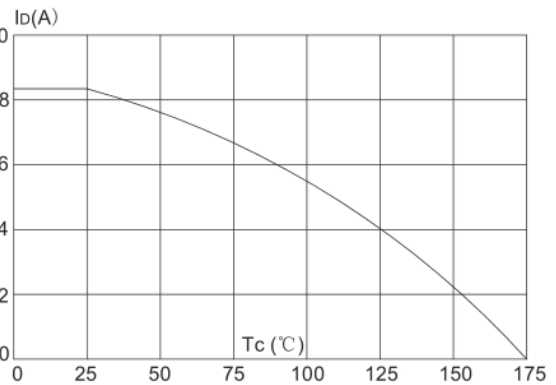
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



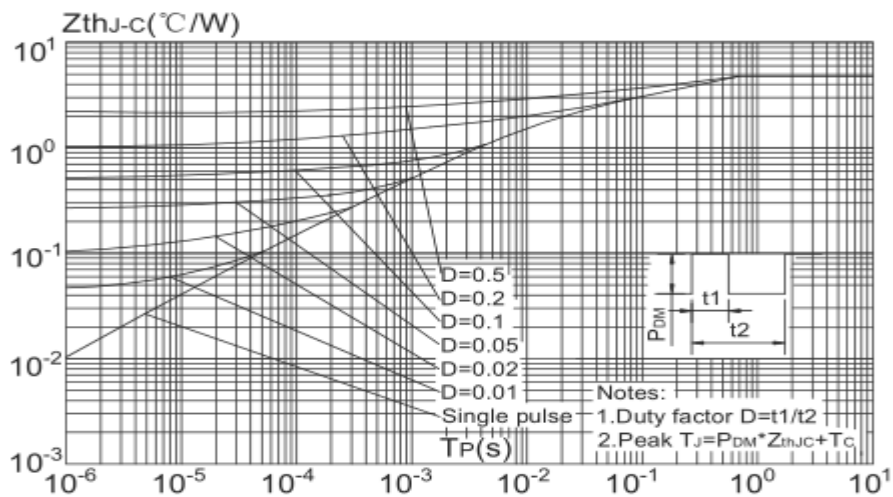
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area

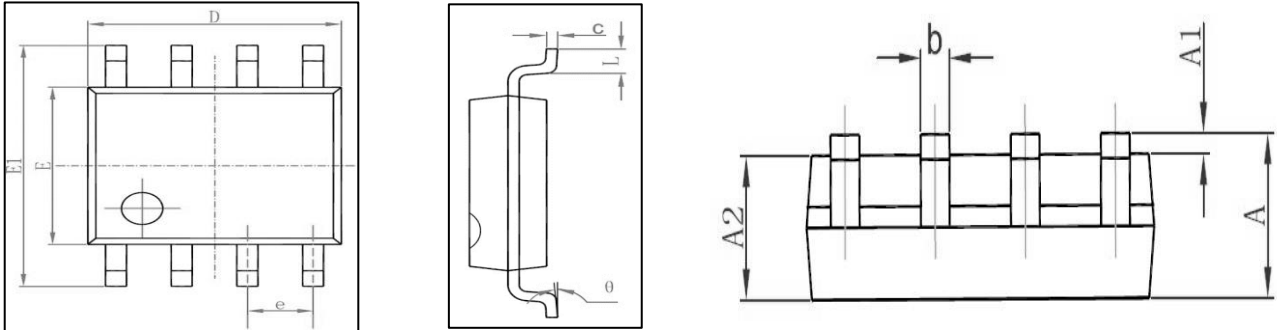


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

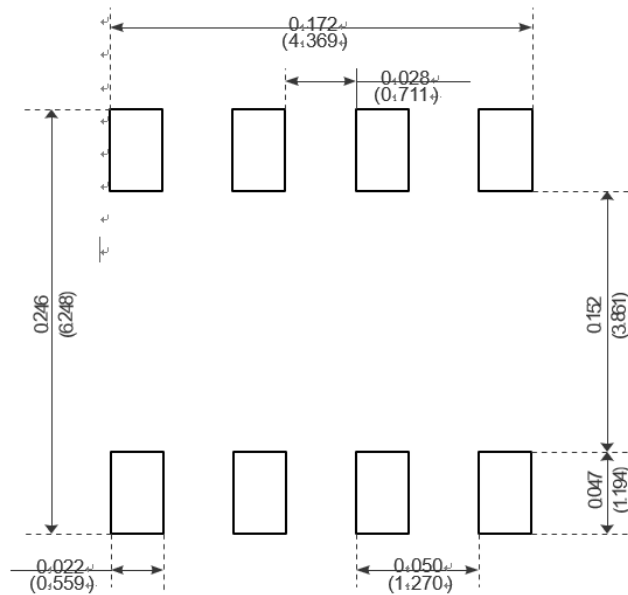


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

**SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads